

SID

Factory: Rot am See

Article:

739

ML4

Provided:

Kracht, Enrico

Customer:

Date:

02.09.2016



Processtechnology: B: undefiniert

Material Text	Mat. Nr.	µm	Stackup	Process overview
---------------	----------	----	---------	------------------

Polyimid 50µ -18µ eins CU Kleberlos 460x305...	50201120	<div>18</div> <div>50</div>	VS	<div>1</div> <div></div>	B00
A-RS-FR4-Prepreg-106-LowFlow-R1551LE	50200912	<div>50</div>		<div>2</div> <div>A01</div>	
C-RS-FR4-DS-1.20mm-018+018-TG150-HF	50200899	<div>18</div>	L2	<div>3</div> <div>A02</div>	
		<div>1164</div>			
		<div>18</div>	L3		
A-RS-FR4-Prepreg-106-TG150-HF	50200640	<div>91</div>		<div>4</div>	
A-RS-FR4-Prepreg-106-TG150-HF	50200640	<div>0</div>		<div>5</div>	
A-RS Kupferfolie-018my 330x490mm	50200238	<div>18</div>	RS	<div>6</div>	

Thickness after Pressing

B00:

1440 µm

Tol+:

155 µm

Tol-:

155 µm

Dmax:

1595 µm

Dmin:

1285 µm

Thickness over all

0 µm

Tol+:

0 µm

Tol-:

0 µm

Dmax:

0 µm

Dmin:

0 µm

Demand for customer

Thickness (D):

1550 µm

Tol+:

155 µm

Tol-:

155 µm

Dmax:

1705 µm

Dmin:

1395 µm

Measuring point: (05) über LM und galv.Cu; beidseitig

nominal:

1427 µm

Version 1.2.16.21

© Würth Elektronik